



Final Product/Process Change Notification

Document #:FPCN26920X

Issue Date:16 Jul 2026

Title of Change:	Additional wafer fabrication facility for T10M_40V (Non- Automotive) technology in onsemi EFK located in East Fishkill, United States.	
Proposed First Ship date:	23 Oct 2026 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	Changed material can be identified by assembly plant code	
Change Category:	Wafer Fab Change, Test Change	
Change Sub-Category(s):	Manufacturing Site Addition, Addition of 12-inch wafers from EFK	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi, East Fishkill	None	
Description and Purpose:		
This Product Change Notification, which is intended to add capacity for onsemi T10 40V MOSFET technology products, is announcing the addition of onsemi East Fishkill, US for the manufacturing of these products. The changes include onsemi East Fishkill as an additional site for wafer fabrication, wafer probe and back grind and back metal, utilizing 300mm diameter wafers, as compared to our existing sites using 200mm wafers. There is no product marking change as a result of this change.		
	Before	After
Wafer fabrication site	onsemi Aizu, Japan	onsemi Aizu, Japan onsemi East Fishkill ,US
Wafer size	200mm	200mm 300mm
Wafer probe site	onsemi Seremban Malaysia	onsemi Seremban, Malaysia onsemi East Fishkill ,US
Backgrind Backmetal site	onsemi Seremban Malaysia	onsemi Seremban, Malaysia onsemi East Fishkill ,US
There is no product marking change as a result of this change		



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Reliability Data Summary:

QV DEVICE NAME: NVMFWS0D4N04XMT1G

RMS: 99275

PACKAGE: S08FL

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta= _175_ °C, _100_% max rated V	1008 hrs	0/231
High Temperature Gate Bias	JESD22-A108	Ta= _175_ °C, 100% max rated Vgss	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 175C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre IOL, TC, uHAST, HAST		0/924
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
NTMFS0D4N04XMT1G	#NONE	NVMFWS0D4N04XMT1G